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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Active
Number of LABs/CLBs	896
Number of Logic Elements/Cells	8064
Total RAM Bits	294912
Number of I/O	264
Number of Gates	400000
Voltage - Supply	1.14V ~ 1.26V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	456-BBGA
Supplier Device Package	456-FBGA (23x23)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xc3s400-5fg456c

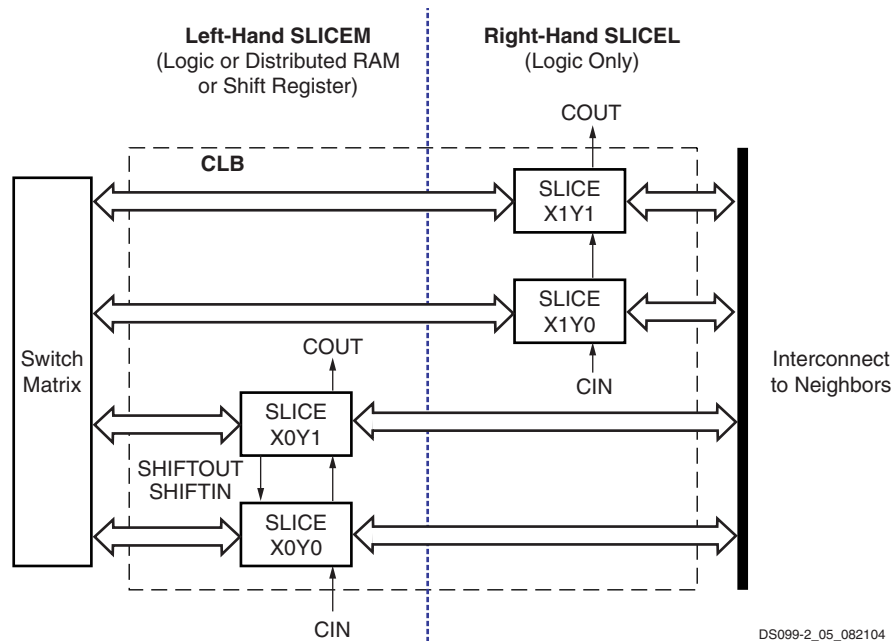


Figure 11: Arrangement of Slices within the CLB

Elements Within a Slice

All four slices have the following elements in common: two logic function generators, two storage elements, wide-function multiplexers, carry logic, and arithmetic gates, as shown in [Figure 12, page 24](#). Both the left-hand and right-hand slice pairs use these elements to provide logic, arithmetic, and ROM functions. Besides these, the left-hand pair supports two additional functions: storing data using Distributed RAM and shifting data with 16-bit registers. [Figure 12](#) is a diagram of the left-hand slice; therefore, it represents a superset of the elements and connections to be found in all slices. See [Function Generator, page 25](#) for more information.

The RAM-based function generator—also known as a Look-Up Table or LUT—is the main resource for implementing logic functions. Furthermore, the LUTs in each left-hand slice pair can be configured as Distributed RAM or a 16-bit shift register. For information on the former, refer to the chapter entitled “Using Look-Up Tables as Distributed RAM” in [UG331](#); for information on the latter, refer to the chapter entitled “Using Look-Up Tables as Shift Registers” in [UG331](#). The function generators located in the upper and lower portions of the slice are referred to as the “G” and “F”, respectively.

The storage element, which is programmable as either a D-type flip-flop or a level-sensitive latch, provides a means for synchronizing data to a clock signal, among other uses. The storage elements in the upper and lower portions of the slice are called FFY and FFX, respectively.

Wide-function multiplexers effectively combine LUTs in order to permit more complex logic operations. Each slice has two of these multiplexers with F5MUX in the lower portion of the slice and F1MUX in the upper portion. Depending on the slice, F1MUX takes on the name F6MUX, F7MUX, or F8MUX. For more details on the multiplexers, refer to the chapter entitled “Using Dedicated Multiplexers” in [UG331](#).

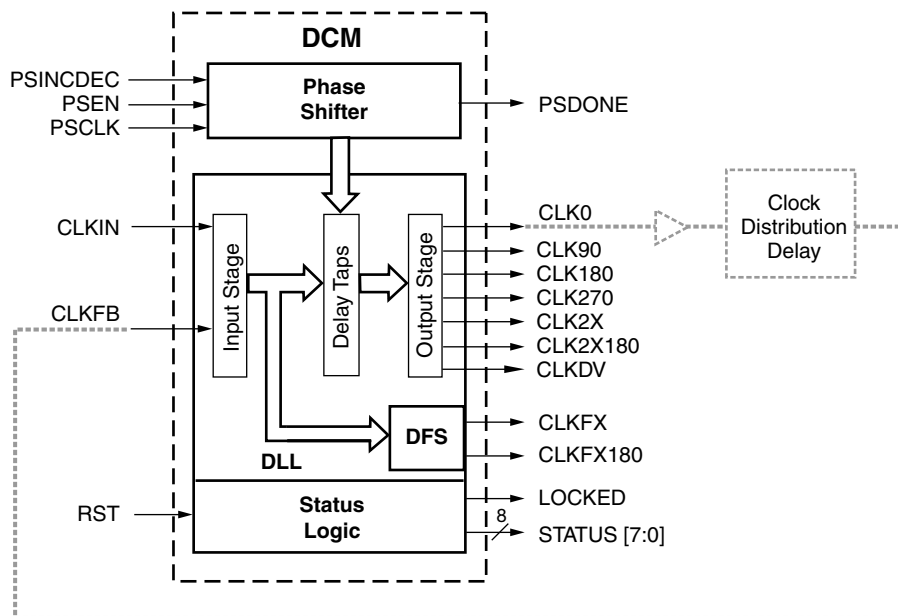
The carry chain, together with various dedicated arithmetic logic gates, support fast and efficient implementations of math operations. The carry chain enters the slice as CIN and exits as COUT. Five multiplexers control the chain: CYINIT, CY0F, and CYMUXF in the lower portion as well as CY0G and CYMUXG in the upper portion. The dedicated arithmetic logic includes the exclusive-OR gates XORG and XORF (upper and lower portions of the slice, respectively) as well as the AND gates GAND and FAND (upper and lower portions, respectively). For more details on the carry logic, refer to the chapter entitled “Using Carry and Arithmetic Logic” in [UG331](#).

Main Logic Paths

Central to the operation of each slice are two nearly identical data paths, distinguished using the terms *top* and *bottom*. The description that follows uses names associated with the bottom path. (The top path names appear in parentheses.) The basic path originates at an interconnect-switch matrix outside the CLB. Four lines, F1 through F4 (or G1 through G4 on the

- **Phase Shifting:** The DCM provides the ability to shift the phase of all its output clock signals with respect to its input clock signal.

The DCM has four functional components: the Delay-Locked Loop (DLL), the Digital Frequency Synthesizer (DFS), the Phase Shifter (PS), and the Status Logic. Each component has its associated signals, as shown in Figure 19.

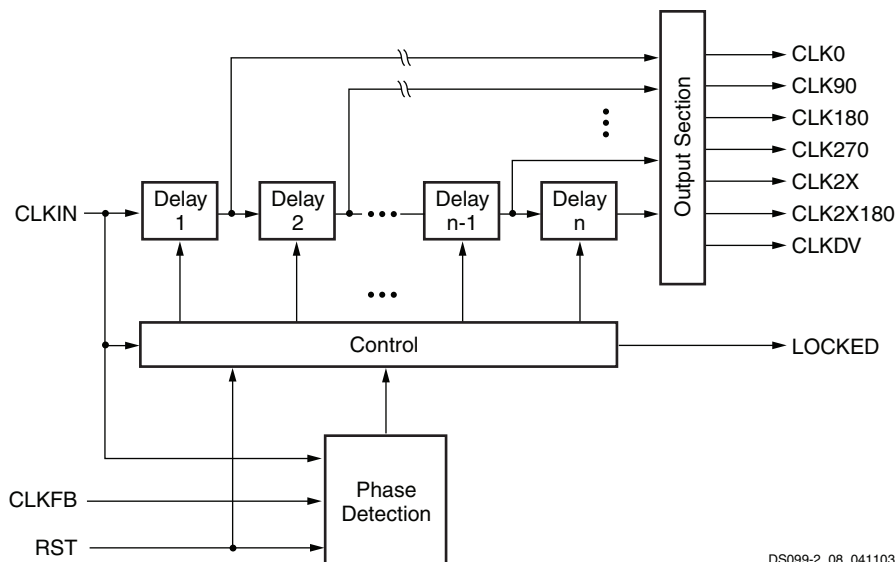


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Figure 19: DCM Functional Blocks and Associated Signals

Delay-Locked Loop (DLL)

The most basic function of the DLL component is to eliminate clock skew. The main signal path of the DLL consists of an input stage, followed by a series of discrete delay elements or *taps*, which in turn leads to an output stage. This path together with logic for phase detection and control forms a system complete with feedback as shown in Figure 20.



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Figure 20: Simplified Functional Diagram of DLL

The output frequency (f_{CLKFX}) can be expressed as a function of the incoming clock frequency (f_{CLKIN}) as follows:

$$f_{\text{CLKFX}} = f_{\text{CLKIN}}(\text{CLKFX_MULTIPLY}/\text{CLKFX_DIVIDE}) \quad \text{Equation 3}$$

Regarding the two attributes, it is possible to assign any combination of integer values, provided that two conditions are met:

- The two values fall within their corresponding ranges, as specified in [Table 18](#).
- The f_{CLKFX} frequency calculated from the above expression accords with the DCM's operating frequency specifications.

For example, if $\text{CLKFX_MULTIPLY} = 5$ and $\text{CLKFX_DIVIDE} = 3$, then the frequency of the output clock signal would be 5/3 that of the input clock signal.

DFS Frequency Modes

The DFS supports two operating modes, High Frequency and Low Frequency, with each specified over a different clock frequency range. The $\text{DFS_FREQUENCY_MODE}$ attribute chooses between the two modes. When the attribute is set to LOW, the Low Frequency mode permits the two DFS outputs to operate over a low-to-moderate frequency range. When the attribute is set to HIGH, the High Frequency mode allows both these outputs to operate at the highest possible frequencies.

DFS With or Without the DLL

The DFS component can be used with or without the DLL component:

Without the DLL, the DFS component multiplies or divides the CLKIN signal frequency according to the respective CLKFX_MULTIPLY and CLKFX_DIVIDE values, generating a clock with the new target frequency on the CLKFX and CLKFX180 outputs. Though classified as belonging to the DLL component, the CLKIN input is shared with the DFS component. This case does not employ feedback loop; therefore, it cannot correct for clock distribution delay.

With the DLL, the DFS operates as described in the preceding case, only with the additional benefit of eliminating the clock distribution delay. In this case, a feedback loop from the CLK0 output to the CLKFB input must be present.

The DLL and DFS components work together to achieve this phase correction as follows: Given values for the CLKFX_MULTIPLY and CLKFX_DIVIDE attributes, the DLL selects the delay element for which the output clock edge coincides with the input clock edge whenever mathematically possible. For example, when $\text{CLKFX_MULTIPLY} = 5$ and $\text{CLKFX_DIVIDE} = 3$, the input and output clock edges will coincide every three input periods, which is equivalent in time to five output periods.

Smaller CLKFX_MULTIPLY and CLKFX_DIVIDE values achieve faster lock times. With no factors common to the two attributes, alignment will occur once with every number of cycles equal to the CLKFX_DIVIDE value. Therefore, it is recommended that the user reduce these values by factoring wherever possible. For example, given $\text{CLKFX_MULTIPLY} = 9$ and $\text{CLKFX_DIVIDE} = 6$, removing a factor of three yields $\text{CLKFX_MULTIPLY} = 3$ and $\text{CLKFX_DIVIDE} = 2$. While both value-pairs will result in the multiplication of clock frequency by 3/2, the latter value-pair will enable the DLL to lock more quickly.

Table 18: DFS Attributes

Attribute	Description	Values
$\text{DFS_FREQUENCY_MODE}$	Chooses between High Frequency and Low Frequency modes	Low, High
CLKFX_MULTIPLY	Frequency multiplier constant	Integer from 2 to 32
CLKFX_DIVIDE	Frequency divisor constant	Integer from 1 to 32

Table 19: DFS Signals

Signal	Direction	Description
CLKFX	Output	Multiplies the CLKIN frequency by the attribute-value ratio ($\text{CLKFX_MULTIPLY}/\text{CLKFX_DIVIDE}$) to generate a clock signal with a new target frequency.
CLKFX180	Output	Generates a clock signal with same frequency as CLKFX, only shifted 180° out-of-phase.

Each BUFGMUX element, shown in [Figure 24](#), is a 2-to-1 multiplexer that can receive signals from any of the four following sources:

- One of the four Global Clock inputs on the same side of the die—top or bottom—as the BUFGMUX element in use.
- Any of four nearby horizontal Double lines.
- Any of four outputs from the DCM in the right-hand quadrant that is on the same side of the die as the BUFGMUX element in use.
- Any of four outputs from the DCM in the left-hand quadrant that is on the same side of the die as the BUFGMUX element in use.

The multiplexer select line, S, chooses which of the two inputs, I0 or I1, drives the BUFGMUX's output signal, O, as described in [Table 25](#). The switching from one clock to the other is glitchless, and done in such a way that the output High and Low times are never shorter than the shortest High or Low time of either input clock.

Table 25: BUFGMUX Select Mechanism

S Input	O Output
0	I0 Input
1	I1 Input

The two clock inputs can be asynchronous with regard to each other, and the S input can change at any time, except for a short setup time prior to the rising edge of the presently selected clock (I0 or I1). Violating this setup time requirement can result in an undefined runt pulse output.

The BUFG clock buffer primitive drives a single clock signal onto the clock network and is essentially the same element as a BUFGMUX, just without the clock select mechanism. Similarly, the BUFGCE primitive creates an enabled clock buffer using the BUFGMUX select mechanism.

Each BUFGMUX buffers incoming clock signals to two possible destinations:

- The vertical spine belonging to the same side of the die—top or bottom—as the BUFGMUX element in use. The two spines—top and bottom—each comprise four vertical clock lines, each running from one of the BUFGMUX elements on the same side towards the center of the die. At the center of the die, clock signals reach the eight-line horizontal spine, which spans the width of the die. In turn, the horizontal spine branches out into a subsidiary clock interconnect that accesses the CLBs.
- The clock input of either DCM on the same side of the die—top or bottom—as the BUFGMUX element in use.

Use either a BUFGMUX element or a BUFG (Global Clock Buffer) element to place a Global input in the design. For the purpose of minimizing the dynamic power dissipation of the clock network, the Xilinx development software automatically disables all clock line segments that a design does not use.

A global clock line ideally drives clock inputs on the various clocked elements within the FPGA, such as CLB or IOB flip-flops or block RAMs. A global clock line also optionally drives combinatorial inputs. However, doing so provides additional loading on the clock line that might also affect clock jitter. Ideally, drive combinatorial inputs using the signal that also drives the input to the BUFGMUX or BUFG element.

For more details, refer to the chapter entitled “Using Global Clock Resources” in [UG331](#).

Interconnect

Interconnect (or routing) passes signals among the various functional elements of Spartan-3 devices. There are four kinds of interconnect: Long lines, Hex lines, Double lines, and Direct lines.

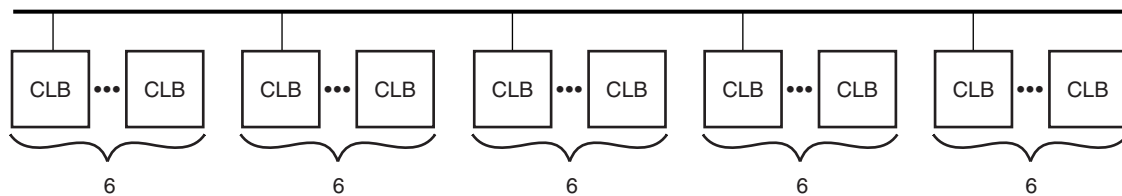
Long lines connect to one out of every six CLBs (see section [a] of Figure 25). Because of their low capacitance, these lines are well-suited for carrying high-frequency signals with minimal loading effects (e.g. skew). If all eight Global Clock Inputs are already committed and there remain additional clock signals to be assigned, Long lines serve as a good alternative.

Hex lines connect one out of every three CLBs (see section [b] of Figure 25). These lines fall between Long lines and Double lines in terms of capability: Hex lines approach the high-frequency characteristics of Long lines at the same time, offering greater connectivity.

Double lines connect to every other CLB (see section [c] of Figure 25). Compared to the types of lines already discussed, Double lines provide a higher degree of flexibility when making connections.

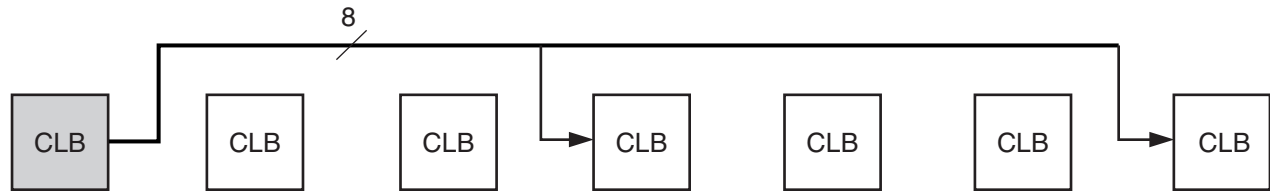
Direct lines afford any CLB direct access to neighboring CLBs (see section [d] of Figure 25). These lines are most often used to conduct a signal from a "source" CLB to a Double, Hex, or Long line and then from the longer interconnect back to a Direct line accessing a "destination" CLB.

For more details, refer to the "Using Interconnect" chapter in [UG331](#).



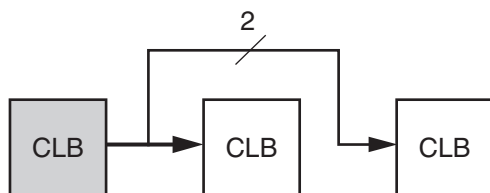
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(a) Long Lines



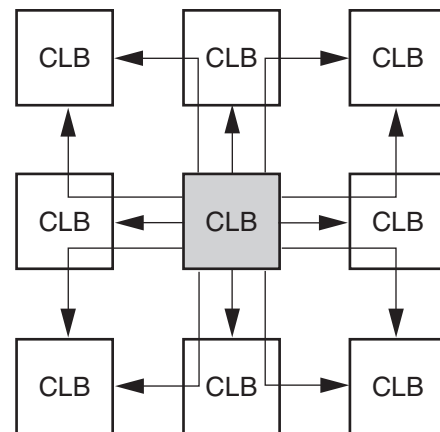
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(b) Hex Lines



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(c) Double Lines



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(d) Direct Lines

Figure 25: Types of Interconnect

Table 28: Absolute Maximum Ratings (Cont'd)

Symbol	Description	Conditions	Min	Max	Units
I_{IK}	Input clamp current per I/O pin	$-0.5\text{ V} < V_{IN} < (V_{CCO} + 0.5\text{ V})$	–	±100	mA
V_{ESD}	Electrostatic Discharge Voltage pins relative to GND	Human body model	–	±2000	V
		Charged device model	–	±500	V
		Machine model	–	±200	V
T_J	Junction temperature		–	125	°C
T_{SOL}	Soldering temperature ⁽⁴⁾		–	220	°C
T_{STG}	Storage temperature		–65	150	°C

Notes:

- Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only; functional operation of the device at these or any other conditions beyond those listed under the Recommended Operating Conditions is not implied. Exposure to Absolute Maximum Ratings conditions for extended periods of time adversely affects device reliability.
- All User I/O and Dual-Purpose pins (DIN/D0, D1–D7, CS_B, RDWR_B, BUSY/DOOUT, and INIT_B) draw power from the V_{CCO} power rail of the associated bank. Keeping V_{IN} within 500 mV of the associated V_{CCO} rails or ground rail ensures that the internal diode junctions that exist between each of these pins and the V_{CCO} and GND rails do not turn on. [Table 32](#) specifies the V_{CCO} range used to determine the max limit. Input voltages outside the -0.5 V to $V_{CCO}+0.5\text{ V}$ voltage range are permissible provided that the I_{IK} input clamp diode rating is met and no more than 100 pins exceed the range simultaneously. Prolonged exposure to such current may compromise device reliability. A sustained current of 10 mA will not compromise device reliability. See [XAPP459](#), *Eliminating I/O Coupling Effects when Interfacing Large-Swing Single-Ended Signals to User I/O Pins on Spartan-3 Generation FPGAs* for more details. The V_{IN} limits apply to both the DC and AC components of signals. Simple application solutions are available that show how to handle overshoot/undershoot as well as achieve PCI compliance. Refer to the following application notes: [XAPP457](#), *Powering and Configuring Spartan-3 Generation FPGAs in Compliant PCI Applications* and [XAPP659](#), *Virtex@-II Pro / Virtex-II Pro X 3.3V I/O Design Guidelines*.
- All Dedicated pins (M0–M2, CCLK, PROG_B, DONE, HSWAP_EN, TCK, TDI, TDO, and TMS) draw power from the V_{CCAUX} rail (2.5V). Meeting the V_{IN} max limit ensures that the internal diode junctions that exist between each of these pins and the V_{CCAUX} rail do not turn on. [Table 32](#) specifies the V_{CCAUX} range used to determine the max limit. When V_{CCAUX} is at its maximum recommended operating level (2.625V), V_{IN} max < 3.125V. As long as the V_{IN} max specification is met, oxide stress is not possible. For information concerning the use of 3.3V signals, see the [3.3V-Tolerant Configuration Interface](#), page 47. See also [XAPP459](#).
- For soldering guidelines, see [UG112](#), *Device Packaging and Thermal Characteristics* and [XAPP427](#), *Implementation and Solder Reflow Guidelines for Pb-Free Packages*.

Table 29: Supply Voltage Thresholds for Power-On Reset

Symbol	Description	Min	Max	Units
V_{CCINTT}	Threshold for the V_{CCINT} supply	0.4	1.0	V
V_{CCAUXT}	Threshold for the V_{CCAUX} supply	0.8	2.0	V
V_{CCO4T}	Threshold for the V_{CCO} Bank 4 supply	0.4	1.0	V

Notes:

- V_{CCINT} , V_{CCAUX} , and V_{CCO} supplies may be applied in any order. When applying V_{CCINT} power before V_{CCAUX} power, the FPGA may draw a *surplus* current in addition to the quiescent current levels specified in [Table 34](#). Applying V_{CCAUX} eliminates the surplus current. The FPGA does not use any of the surplus current for the power-on process. For this power sequence, make sure that regulators with foldback features will not shut down inadvertently.
- To ensure successful power-on, V_{CCINT} , V_{CCO} Bank 4, and V_{CCAUX} supplies must rise through their respective threshold-voltage ranges with no dips at any point.
- If a brown-out condition occurs where V_{CCAUX} or V_{CCINT} drops below the retention voltage indicated in [Table 31](#), then V_{CCAUX} or V_{CCINT} must drop below the minimum power-on reset voltage in order to clear out the device configuration content.

Table 34: Quiescent Supply Current Characteristics

Symbol	Description	Device	Typical ⁽¹⁾	Commercial Maximum ⁽¹⁾	Industrial Maximum ⁽¹⁾	Units
I_{CCINTQ}	Quiescent V_{CCINT} supply current	XC3S50	5	24	31	mA
		XC3S200	10	54	80	mA
		XC3S400	15	110	157	mA
		XC3S1000	35	160	262	mA
		XC3S1500	45	260	332	mA
		XC3S2000	60	360	470	mA
		XC3S4000	100	450	810	mA
		XC3S5000	120	600	870	mA
I_{CCOQ}	Quiescent V_{CCO} supply current	XC3S50	1.5	2.0	2.5	mA
		XC3S200	1.5	3.0	3.5	mA
		XC3S400	1.5	3.0	3.5	mA
		XC3S1000	2.0	4.0	5.0	mA
		XC3S1500	2.5	4.0	5.0	mA
		XC3S2000	3.0	5.0	6.0	mA
		XC3S4000	3.5	5.0	6.0	mA
		XC3S5000	3.5	5.0	6.0	mA
I_{CCAUXQ}	Quiescent V_{CCAUX} supply current	XC3S50	7	20	22	mA
		XC3S200	10	30	33	mA
		XC3S400	15	40	44	mA
		XC3S1000	20	50	55	mA
		XC3S1500	35	75	85	mA
		XC3S2000	45	90	100	mA
		XC3S4000	55	110	125	mA
		XC3S5000	70	130	145	mA

Notes:

- The numbers in this table are based on the conditions set forth in [Table 32](#). Quiescent supply current is measured with all I/O drivers in a high-impedance state and with all pull-up/pull-down resistors at the I/O pads disabled. Typical values are characterized using devices with typical processing at room temperature (T_J of 25°C at $V_{CCINT} = 1.2V$, $V_{CCO} = 3.3V$, and $V_{CCAUX} = 2.5V$). Maximum values are the production test limits measured for each device at the maximum specified junction temperature and at maximum voltage limits with $V_{CCINT} = 1.26V$, $V_{CCO} = 3.465V$, and $V_{CCAUX} = 2.625V$. The FPGA is programmed with a "blank" configuration data file (i.e., a design with no functional elements instantiated). For conditions other than those described above, (e.g., a design including functional elements, the use of DCI standards, etc.), measured quiescent current levels may be different than the values in the table. Use the XPower Estimator or XPower Analyzer for more accurate estimates. See Note 2.
- There are two recommended ways to estimate the total power consumption (quiescent plus dynamic) for a specific design: a) The [Spartan-3 XPower Estimator](#) provides quick, approximate, typical estimates, and does not require a netlist of the design. b) XPower Analyzer, part of the Xilinx ISE development software, uses the FPGA netlist as input to provide more accurate maximum and typical estimates.
- The maximum numbers in this table also indicate the minimum current each power rail requires in order for the FPGA to power-on successfully, once all three rails are supplied. If V_{CCINT} is applied before V_{CCAUX} , there may be temporary additional I_{CCINT} current until V_{CCAUX} is applied. See [Surplus \$I_{CCINT}\$ if \$V_{CCINT}\$ Applied before \$V_{CCAUX}\$, page 54](#)

Table 48: Test Methods for Timing Measurement at I/Os (Cont'd)

Signal Standard (IOSTANDARD)	Inputs			Outputs		Inputs and Outputs
	V_{REF} (V)	V_L (V)	V_H (V)	R_T (Ω)	V_T (V)	V_M (V)
DIFF_SSTL2_II	-	$V_{ICM} - 0.75$	$V_{ICM} + 0.75$	50	1.25	V_{ICM}
DIFF_SSTL2_II_DCI						

Notes:

- Descriptions of the relevant symbols are as follows:
 V_{REF} – The reference voltage for setting the input switching threshold
 V_{ICM} – The common mode input voltage
 V_M – Voltage of measurement point on signal transition
 V_L – Low-level test voltage at Input pin
 V_H – High-level test voltage at Input pin
 R_T – Effective termination resistance, which takes on a value of 1MW when no parallel termination is required
 V_T – Termination voltage
- The load capacitance (CL) at the Output pin is 0 pF for all signal standards.
- According to the PCI specification.

The capacitive load (C_L) is connected between the output and GND. *The Output timing for all standards, as published in the speed files and the data sheet, is always based on a C_L value of zero.* High-impedance probes (less than 1 pF) are used for all measurements. Any delay that the test fixture might contribute to test measurements is subtracted from those measurements to produce the final timing numbers as published in the speed files and data sheet.

Using IBIS Models to Simulate Load Conditions in Application

IBIS Models permit the most accurate prediction of timing delays for a given application. The parameters found in the IBIS model (V_{REF} , R_{REF} , and V_{MEAS}) correspond directly with the parameters used in Table 48, V_T , R_T , and V_M . Do not confuse V_{REF} (the termination voltage) from the IBIS model with V_{REF} (the input-switching threshold) from the table. A fourth parameter, C_{REF} is always zero. The four parameters describe all relevant output test conditions. IBIS models are found in the Xilinx development software as well as at the following link.

<http://www.xilinx.com/support/download/index.htm>

Simulate delays for a given application according to its specific load conditions as follows:

- Simulate the desired signal standard with the output driver connected to the test setup shown in Figure 35. Use parameter values V_T , R_T , and V_M from Table 48. C_{REF} is zero.
- Record the time to V_M .
- Simulate the same signal standard with the output driver connected to the PCB trace with load. Use the appropriate IBIS model (including V_{REF} , R_{REF} , C_{REF} , and V_{MEAS} values) or capacitive value to represent the load.
- Record the time to V_{MEAS} .
- Compare the results of steps 2 and 4. The increase (or decrease) in delay should be added to (or subtracted from) the appropriate Output standard adjustment (Table 47) to yield the worst-case delay of the PCB trace.

Table 59: Switching Characteristics for the DLL

Symbol	Description	Frequency Mode / FCLKIN Range	Device	Speed Grade				Units
				-5		-4		
				Min	Max	Min	Max	
Output Frequency Ranges								
CLKOUT_FREQ_1X_LF	Frequency for the CLK0, CLK90, CLK180, and CLK270 outputs	Low	All	18	167	18	167	MHz
CLKOUT_FREQ_1X_HF	Frequency for the CLK0 and CLK180 outputs	High		48	280	48	280	MHz
CLKOUT_FREQ_2X_LF ⁽³⁾	Frequency for the CLK2X and CLK2X180 outputs	Low		36	334	36	334	MHz
CLKOUT_FREQ_DV_LF	Frequency for the CLKDV output	Low		1.125	110	1.125	110	MHz
CLKOUT_FREQ_DV_HF		High		3	185	3	185	MHz
Output Clock Jitter ⁽⁴⁾								
CLKOUT_PER_JITT_0	Period jitter at the CLK0 output	All	All	—	±100	—	±100	ps
CLKOUT_PER_JITT_90	Period jitter at the CLK90 output			—	±150	—	±150	ps
CLKOUT_PER_JITT_180	Period jitter at the CLK180 output			—	±150	—	±150	ps
CLKOUT_PER_JITT_270	Period jitter at the CLK270 output			—	±150	—	±150	ps
CLKOUT_PER_JITT_2X	Period jitter at the CLK2X and CLK2X180 outputs			—	±200	—	±200	ps
CLKOUT_PER_JITT_DV1	Period jitter at the CLKDV output when performing integer division			—	±150	—	±150	ps
CLKOUT_PER_JITT_DV2	Period jitter at the CLKDV output when performing non-integer division			—	±300	—	±300	ps
Duty Cycle								
CLKOUT_DUTY_CYCLE_DLL ⁽⁵⁾	Duty cycle variation for the CLK0, CLK90, CLK180, CLK270, CLK2X, CLK2X180, and CLKDV outputs	All	XC3S50	—	±150	—	±150	ps
			XC3S200	—	±150	—	±150	ps
			XC3S400	—	±250	—	±250	ps
			XC3S1000	—	±400	—	±400	ps
			XC3S1500	—	±400	—	±400	ps
			XC3S2000	—	±400	—	±400	ps
			XC3S4000	—	±400	—	±400	ps
			XC3S5000	—	±400	—	±400	ps
Phase Alignment								
CLKIN_CLKFB_PHASE	Phase offset between the CLKIN and CLKFB inputs	All	All	—	±150	—	±150	ps
CLKOUT_PHASE	Phase offset between any two DLL outputs (except CLK2X and CLK0)			—	±140	—	±140	ps
	Phase offset between the CLK2X and CLK0 outputs			—	±250	—	±250	ps

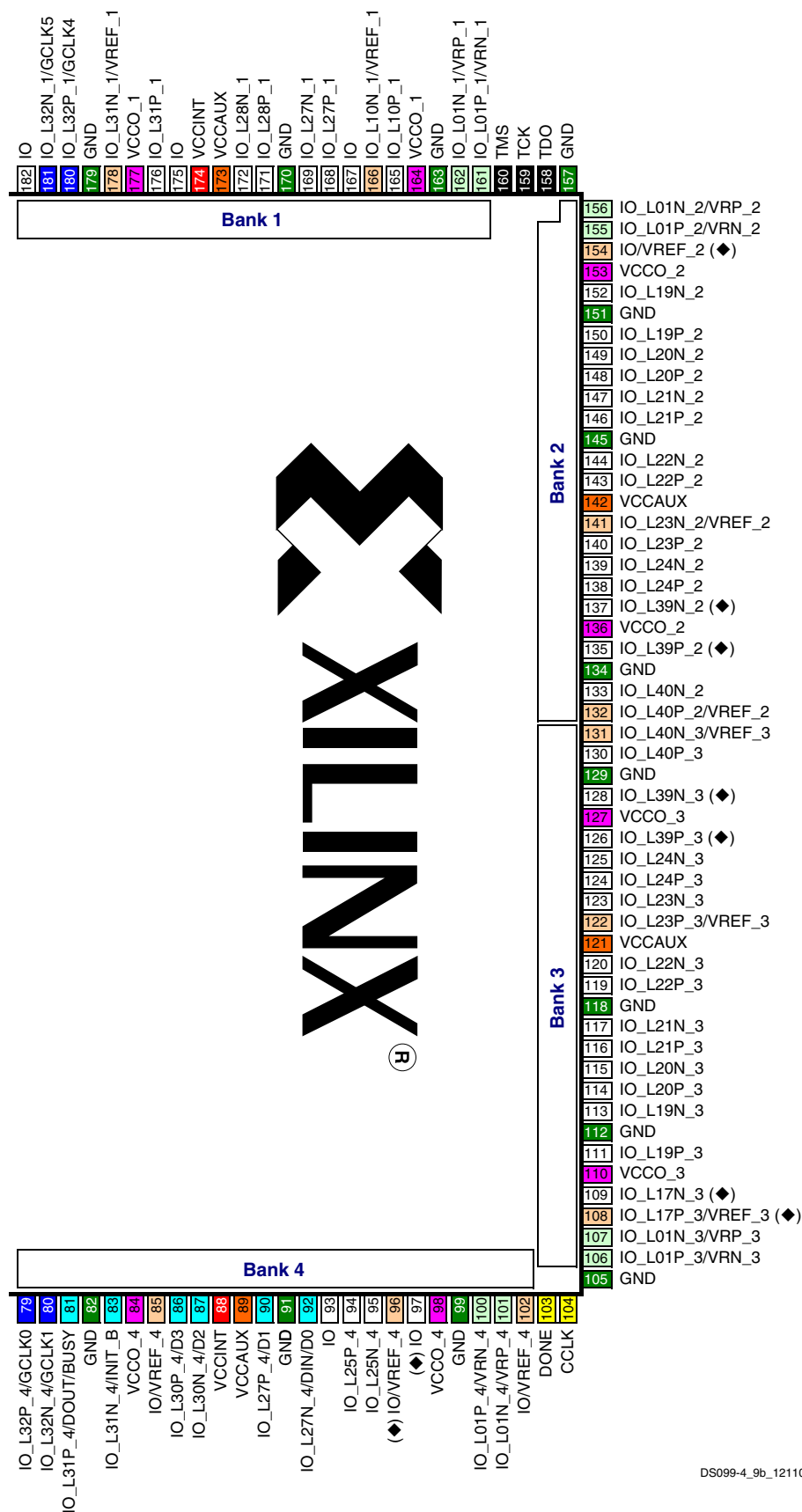
Date	Version	Description
05/25/07	2.2	Improved absolute maximum voltage specifications in Table 28 , providing additional overshoot allowance. Improved XC3S50 HBM ESD to 2000V in Table 28 . Based on extensive 90 nm production data, improved (reduced) the maximum quiescent current limits for the I_{CCINTQ} and I_{CCOQ} specifications in Table 34 . Widened the recommended voltage range for the PCI standard and clarified the hysteresis footnote in Table 35 . Noted restriction on combining differential outputs in Table 38 . Updated footnote 1 in Table 64 .
11/30/07	2.3	Updated 3.3V VCCO max from 3.45V to 3.465V in Table 32 and elsewhere. Reduced t_{ICCK} minimum from 0.50 μ s to 0.25 μ s in Table 65 . Updated links to technical documentation.
06/25/08	2.4	Clarified dual marking. Added Mask and Fab Revisions . Added references to XAPP459 in Table 28 and Table 32 . Removed absolute minimum and added footnote referring to timing analyzer for minimum delay values. Added HSLVDCI to Table 48 and Table 50 . Updated t_{DICK} in Table 51 to match largest possible value in speed file. Updated formatting and links.
12/04/09	2.5	Updated notes 2 and 3 in Table 28 . Removed silicon process specific information and revised notes in Table 30 . Updated note 3 in Table 32 . Updated note 3 in Table 34 . Updated note 5 in Table 35 . Updated V_{OL} max and V_{OH} min for SSTL2_II in Table 36 . Updated note 5 in Table 36 . Updated JTAG Waveforms in Figure 39 . Updated V_{ICM} max for LVPECL_25 in Table 37 . Updated RT and VT for LVDS_25_DCI in Table 48 . Updated Simultaneously Switching Output Guidelines . Noted that the CP132 package is being discontinued in Table 49 . Removed minimum values for T_{MULTCK} clock-to-output times in Table 54 . Updated footnote 3 in Table 58 . Removed minimum values for T_{MULT} propagation times in Table 55 . Removed silicon process specific information and revised notes in Table 61 . Updated Phase Shifter (PS) .
10/29/12	3.0	Added Notice of Disclaimer . Per XCN07022 , updated the discontinued FG1156 and FGG1156 package discussion throughout document. Per XCN08011 , updated the discontinued CP132 and CPG132 package discussion throughout document. Revised description of V_{IN} in Table 32 and added note 7. Added note 4 to Table 33 . This product is not recommended for new designs.

Table 79: Pin Behavior After Power-Up, During Configuration (Cont'd)

Pin Name	Configuration Mode Settings <M2:M1:M0>					Bitstream Configuration Option
	Serial Modes		SelectMap Parallel Modes		JTAG Mode <1:0:1>	
	Master <0:0:0>	Slave <1:1:1>	Master <0:1:1>	Slave <1:1:0>		
JTAG: JTAG interface pins (pull-up resistor to VCCAUX always active during configuration, regardless of HSWAP_EN pin)						
TDI	TDI (I)	TDI (I)	TDI (I)	TDI (I)	TDI (I)	TdiPin
TMS	TMS (I)	TMS (I)	TMS (I)	TMS (I)	TMS (I)	TmsPin
TCK	TCK (I)	TCK (I)	TCK (I)	TCK (I)	TCK (I)	TckPin
TDO	TDO (O)	TDO (O)	TDO (O)	TDO (O)	TDO (O)	TdoPin

Table 93: PQ208 Package Pinout (Cont'd)

Bank	XC3S50 Pin Name	XC3S200, XC3S400 Pin Names	PQ208 Pin Number	Type
3	IO_L20P_3	IO_L20P_3	P114	I/O
3	IO_L21N_3	IO_L21N_3	P117	I/O
3	IO_L21P_3	IO_L21P_3	P116	I/O
3	IO_L22N_3	IO_L22N_3	P120	I/O
3	IO_L22P_3	IO_L22P_3	P119	I/O
3	IO_L23N_3	IO_L23N_3	P123	I/O
3	IO_L23P_3/VREF_3	IO_L23P_3/VREF_3	P122	VREF
3	IO_L24N_3	IO_L24N_3	P125	I/O
3	IO_L24P_3	IO_L24P_3	P124	I/O
3	N.C. (◆)	IO_L39N_3	P128	I/O
3	N.C. (◆)	IO_L39P_3	P126	I/O
3	IO_L40N_3/VREF_3	IO_L40N_3/VREF_3	P131	VREF
3	IO_L40P_3	IO_L40P_3	P130	I/O
3	VCCO_3	VCCO_3	P110	VCCO
3	VCCO_3	VCCO_3	P127	VCCO
4	IO	IO	P93	I/O
4	N.C. (◆)	IO	P97	I/O
4	IO/VREF_4	IO/VREF_4	P85	VREF
4	N.C. (◆)	IO/VREF_4	P96	VREF
4	IO/VREF_4	IO/VREF_4	P102	VREF
4	IO_L01N_4/VRP_4	IO_L01N_4/VRP_4	P101	DCI
4	IO_L01P_4/VRN_4	IO_L01P_4/VRN_4	P100	DCI
4	IO_L25N_4	IO_L25N_4	P95	I/O
4	IO_L25P_4	IO_L25P_4	P94	I/O
4	IO_L27N_4/DIN/D0	IO_L27N_4/DIN/D0	P92	DUAL
4	IO_L27P_4/D1	IO_L27P_4/D1	P90	DUAL
4	IO_L30N_4/D2	IO_L30N_4/D2	P87	DUAL
4	IO_L30P_4/D3	IO_L30P_4/D3	P86	DUAL
4	IO_L31N_4/INIT_B	IO_L31N_4/INIT_B	P83	DUAL
4	IO_L31P_4/DOUT/BUSY	IO_L31P_4/DOUT/BUSY	P81	DUAL
4	IO_L32N_4/GCLK1	IO_L32N_4/GCLK1	P80	GCLK
4	IO_L32P_4/GCLK0	IO_L32P_4/GCLK0	P79	GCLK
4	VCCO_4	VCCO_4	P84	VCCO
4	VCCO_4	VCCO_4	P98	VCCO
5	IO	IO	P63	I/O
5	IO	IO	P71	I/O
5	IO/VREF_5	IO/VREF_5	P78	VREF
5	IO_L01N_5/RDWR_B	IO_L01N_5/RDWR_B	P58	DUAL
5	IO_L01P_5/CS_B	IO_L01P_5/CS_B	P57	DUAL
5	IO_L10N_5/VRP_5	IO_L10N_5/VRP_5	P62	DCI



Right Half of Package
(Top View)

Figure 48: PQ208 Package Footprint (Top View) Continued

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FT256: 256-lead Fine-pitch Thin Ball Grid Array

The 256-lead fine-pitch thin ball grid array package, FT256, supports three different Spartan-3 devices, including the XC3S200, the XC3S400, and the XC3S1000. The footprints for all three devices are identical, as shown in [Table 96](#) and [Figure 49](#).

All the package pins appear in [Table 96](#) and are sorted by bank number, then by pin name. Pairs of pins that form a differential I/O pair appear together in the table. The table also shows the pin number for each pin and the pin type, as defined earlier.

An electronic version of this package pinout table and footprint diagram is available for download from the Xilinx website at http://www.xilinx.com/support/documentation/data_sheets/s3_pin.zip.

Pinout Table

Table 96: FT256 Package Pinout

Bank	XC3S200, XC3S400, XC3S1000 Pin Name	FT256 Pin Number	Type
0	IO	A5	I/O
0	IO	A7	I/O
0	IO/VREF_0	A3	VREF
0	IO/VREF_0	D5	VREF
0	IO_L01N_0/VRP_0	B4	DCI
0	IO_L01P_0/VRN_0	A4	DCI
0	IO_L25N_0	C5	I/O
0	IO_L25P_0	B5	I/O
0	IO_L27N_0	E6	I/O
0	IO_L27P_0	D6	I/O
0	IO_L28N_0	C6	I/O
0	IO_L28P_0	B6	I/O
0	IO_L29N_0	E7	I/O
0	IO_L29P_0	D7	I/O
0	IO_L30N_0	C7	I/O
0	IO_L30P_0	B7	I/O
0	IO_L31N_0	D8	I/O
0	IO_L31P_0/VREF_0	C8	VREF
0	IO_L32N_0/GCLK7	B8	GCLK
0	IO_L32P_0/GCLK6	A8	GCLK
0	VCCO_0	E8	VCCO
0	VCCO_0	F7	VCCO
0	VCCO_0	F8	VCCO
1	IO	A9	I/O
1	IO	A12	I/O
1	IO	C10	I/O
1	IO/VREF_1	D12	VREF
1	IO_L01N_1/VRP_1	A14	DCI
1	IO_L01P_1/VRN_1	B14	DCI

Table 98: FG320 Package Pinout (Cont'd)

Bank	XC3S400, XC3S1000, XC3S1500 Pin Name	FG320 Pin Number	Type
2	IO_L20N_2	E17	I/O
2	IO_L20P_2	E18	I/O
2	IO_L21N_2	F15	I/O
2	IO_L21P_2	E15	I/O
2	IO_L22N_2	F14	I/O
2	IO_L22P_2	G14	I/O
2	IO_L23N_2/VREF_2	G18	VREF
2	IO_L23P_2	F17	I/O
2	IO_L24N_2	G15	I/O
2	IO_L24P_2	G16	I/O
2	IO_L27N_2	H13	I/O
2	IO_L27P_2	H14	I/O
2	IO_L34N_2/VREF_2	H16	VREF
2	IO_L34P_2	H15	I/O
2	IO_L35N_2	H17	I/O
2	IO_L35P_2	H18	I/O
2	IO_L39N_2	J18	I/O
2	IO_L39P_2	J17	I/O
2	IO_L40N_2	J15	I/O
2	IO_L40P_2/VREF_2	J14	VREF
2	VCCO_2	F16	VCCO
2	VCCO_2	H12	VCCO
2	VCCO_2	J12	VCCO
3	IO	K15	I/O
3	IO_L01N_3/VRP_3	T17	DCI
3	IO_L01P_3/VRN_3	T16	DCI
3	IO_L16N_3	T18	I/O
3	IO_L16P_3	U18	I/O
3	IO_L17N_3	P16	I/O
3	IO_L17P_3/VREF_3	R16	VREF
3	IO_L19N_3	R17	I/O
3	IO_L19P_3	R18	I/O
3	IO_L20N_3	P18	I/O
3	IO_L20P_3	P17	I/O
3	IO_L21N_3	P15	I/O
3	IO_L21P_3	N15	I/O
3	IO_L22N_3	M14	I/O
3	IO_L22P_3	N14	I/O
3	IO_L23N_3	M15	I/O
3	IO_L23P_3/VREF_3	M16	VREF

Table 98: FG320 Package Pinout (Cont'd)

Bank	XC3S400, XC3S1000, XC3S1500 Pin Name	FG320 Pin Number	Type
N/A	VCCINT	N6	VCCINT
N/A	VCCINT	N7	VCCINT
VCCAUX	CCLK	T15	CONFIG
VCCAUX	DONE	R15	CONFIG
VCCAUX	HSWAP_EN	E6	CONFIG
VCCAUX	M0	P5	CONFIG
VCCAUX	M1	U3	CONFIG
VCCAUX	M2	R4	CONFIG
VCCAUX	PROG_B	E5	CONFIG
VCCAUX	TCK	E14	JTAG
VCCAUX	TDI	D4	JTAG
VCCAUX	TDO	D15	JTAG
VCCAUX	TMS	B16	JTAG

User I/Os by Bank

Table 99 indicates how the available user-I/O pins are distributed between the eight I/O banks on the FG320 package.

Table 99: User I/Os Per Bank in FG320 Package

Package Edge	I/O Bank	Maximum I/O	Maximum LVDS Pairs	All Possible I/O Pins by Type				
				I/O	DUAL	DCI	VREF	GCLK
Top	0	26	11	19	0	2	3	2
	1	26	11	19	0	2	3	2
Right	2	29	14	23	0	2	4	0
	3	29	14	23	0	2	4	0
Bottom	4	27	11	13	6	2	4	2
	5	26	11	13	6	2	3	2
Left	6	29	14	23	0	2	4	0
	7	29	14	23	0	2	4	0

Table 103: FG676 Package Pinout (Cont'd)

Bank	XC3S1000 Pin Name	XC3S1500 Pin Name	XC3S2000 Pin Name	XC3S4000 Pin Name	XC3S5000 Pin Name	FG676 Pin Number	Type
7	IO_L01P_7/VRN_7	IO_L01P_7/VRN_7	IO_L01P_7/VRN_7	IO_L01P_7/VRN_7	IO_L01P_7/VRN_7	F6	DCI
7	IO_L02N_7	IO_L02N_7	IO_L02N_7	IO_L02N_7	IO_L02N_7	E3	I/O
7	IO_L02P_7	IO_L02P_7	IO_L02P_7	IO_L02P_7	IO_L02P_7	E4	I/O
7	IO_L03N_7/VREF_7	IO_L03N_7/VREF_7	IO_L03N_7/VREF_7	IO_L03N_7/VREF_7	IO_L03N_7/VREF_7	D1	VREF
7	IO_L03P_7	IO_L03P_7	IO_L03P_7	IO_L03P_7	IO_L03P_7	D2	I/O
7	N.C. (◆)	IO_L05N_7	IO_L05N_7	IO_L05N_7	IO_L05N_7	G6	I/O
7	N.C. (◆)	IO_L05P_7	IO_L05P_7	IO_L05P_7	IO_L05P_7	G7	I/O
7	N.C. (◆)	IO_L06N_7	IO_L06N_7	IO_L06N_7	IO_L06N_7	E1	I/O
7	N.C. (◆)	IO_L06P_7	IO_L06P_7	IO_L06P_7	IO_L06P_7	E2	I/O
7	N.C. (◆)	IO_L07N_7	IO_L07N_7	IO_L07N_7	IO_L07N_7	F3	I/O
7	N.C. (◆)	IO_L07P_7	IO_L07P_7	IO_L07P_7	IO_L07P_7	F4	I/O
7	N.C. (◆)	IO_L08N_7	IO_L08N_7	IO_L08N_7	IO_L08N_7	G4	I/O
7	N.C. (◆)	IO_L08P_7	IO_L08P_7	IO_L08P_7	IO_L08P_7	G5	I/O
7	N.C. (◆)	IO_L09N_7	IO_L09N_7	IO_L09N_7	IO_L09N_7	F1	I/O
7	N.C. (◆)	IO_L09P_7	IO_L09P_7	IO_L09P_7	IO_L09P_7	F2	I/O
7	N.C. (◆)	IO_L10N_7	IO_L10N_7	IO_L10N_7	IO_L10N_7	H6	I/O
7	N.C. (◆)	IO_L10P_7/VREF_7	IO_L10P_7/VREF_7	IO_L10P_7/VREF_7	IO_L10P_7/VREF_7	H7	VREF
7	IO_L14N_7	IO_L14N_7	IO_L14N_7	IO_L14N_7	IO_L14N_7	G1	I/O
7	IO_L14P_7	IO_L14P_7	IO_L14P_7	IO_L14P_7	IO_L14P_7	G2	I/O
7	IO_L16N_7	IO_L16N_7	IO_L16N_7	IO_L16N_7	IO_L16N_7	J6	I/O
7	IO_L16P_7/VREF_7	IO_L16P_7/VREF_7	IO_L16P_7/VREF_7	IO_L16P_7/VREF_7	IO_L16P_7/VREF_7	H5	VREF
7	IO_L17N_7	IO_L17N_7	IO_L17N_7	IO_L17N_7	IO_L17N_7	H3	I/O
7	IO_L17P_7	IO_L17P_7	IO_L17P_7	IO_L17P_7	IO_L17P_7	H4	I/O
7	IO_L19N_7/VREF_7	IO_L19N_7/VREF_7	IO_L19N_7/VREF_7	IO_L19N_7/VREF_7	IO_L19N_7/VREF_7	H1	VREF
7	IO_L19P_7	IO_L19P_7	IO_L19P_7	IO_L19P_7	IO_L19P_7	H2	I/O
7	IO_L20N_7	IO_L20N_7	IO_L20N_7	IO_L20N_7	IO_L20N_7	K7	I/O
7	IO_L20P_7	IO_L20P_7	IO_L20P_7	IO_L20P_7	IO_L20P_7	J7	I/O
7	IO_L21N_7	IO_L21N_7	IO_L21N_7	IO_L21N_7	IO_L21N_7	J4	I/O
7	IO_L21P_7	IO_L21P_7	IO_L21P_7	IO_L21P_7	IO_L21P_7	J5	I/O
7	IO_L22N_7	IO_L22N_7	IO_L22N_7	IO_L22N_7	IO_L22N_7	J2	I/O
7	IO_L22P_7	IO_L22P_7	IO_L22P_7	IO_L22P_7	IO_L22P_7	J3	I/O
7	IO_L23N_7	IO_L23N_7	IO_L23N_7	IO_L23N_7	IO_L23N_7	K5	I/O
7	IO_L23P_7	IO_L23P_7	IO_L23P_7	IO_L23P_7	IO_L23P_7	K6	I/O
7	IO_L24N_7	IO_L24N_7	IO_L24N_7	IO_L24N_7	IO_L24N_7	K3	I/O
7	IO_L24P_7	IO_L24P_7	IO_L24P_7	IO_L24P_7	IO_L24P_7	K4	I/O
7	IO_L26N_7	IO_L26N_7	IO_L26N_7	IO_L26N_7	IO_L26N_7	K1	I/O
7	IO_L26P_7	IO_L26P_7	IO_L26P_7	IO_L26P_7	IO_L26P_7	K2	I/O
7	IO_L27N_7	IO_L27N_7	IO_L27N_7	IO_L27N_7	IO_L27N_7	L7	I/O
7	IO_L27P_7/VREF_7	IO_L27P_7/VREF_7	IO_L27P_7/VREF_7	IO_L27P_7/VREF_7	IO_L27P_7/VREF_7	L8	VREF
7	IO_L28N_7	IO_L28N_7	IO_L28N_7	IO_L28N_7	IO_L28N_7	L5	I/O
7	IO_L28P_7	IO_L28P_7	IO_L28P_7	IO_L28P_7	IO_L28P_7	L6	I/O
7	IO_L29N_7	IO_L29N_7	IO_L29N_7	IO_L29N_7	IO_L29N_7	L1	I/O

Table 107: FG900 Package Pinout (Cont'd)

Bank	XC3S2000 Pin Name	XC3S4000, XC3S5000 Pin Name	FG900 Pin Number	Type
5	IO_L07N_5	IO_L07N_5	AK8	I/O
5	IO_L07P_5	IO_L07P_5	AJ8	I/O
5	IO_L08N_5	IO_L08N_5	AC9	I/O
5	IO_L08P_5	IO_L08P_5	AB9	I/O
5	IO_L09N_5	IO_L09N_5	AG9	I/O
5	IO_L09P_5	IO_L09P_5	AF9	I/O
5	IO_L10N_5/VRP_5	IO_L10N_5/VRP_5	AK9	DCI
5	IO_L10P_5/VRN_5	IO_L10P_5/VRN_5	AJ9	DCI
5	IO_L11N_5/VREF_5	IO_L11N_5/VREF_5	AE10	VREF
5	IO_L11P_5	IO_L11P_5	AE9	I/O
5	IO_L12N_5	IO_L12N_5	AJ10	I/O
5	IO_L12P_5	IO_L12P_5	AH10	I/O
5	IO_L13N_5	IO_L13N_5	AD11	I/O
5	IO_L13P_5	IO_L13P_5	AD10	I/O
5	IO_L14N_5	IO_L14N_5	AF11	I/O
5	IO_L14P_5	IO_L14P_5	AE11	I/O
5	IO_L15N_5	IO_L15N_5	AH11	I/O
5	IO_L15P_5	IO_L15P_5	AG11	I/O
5	IO_L16N_5	IO_L16N_5	AK11	I/O
5	IO_L16P_5	IO_L16P_5	AJ11	I/O
5	IO_L17N_5	IO_L17N_5	AB12	I/O
5	IO_L17P_5	IO_L17P_5	AC11	I/O
5	IO_L18N_5	IO_L18N_5	AD12	I/O
5	IO_L18P_5	IO_L18P_5	AC12	I/O
5	IO_L19N_5	IO_L19N_5	AF12	I/O
5	IO_L19P_5/VREF_5	IO_L19P_5/VREF_5	AE12	VREF
5	IO_L20N_5	IO_L20N_5	AH12	I/O
5	IO_L20P_5	IO_L20P_5	AG12	I/O
5	IO_L21N_5	IO_L21N_5	AK12	I/O
5	IO_L21P_5	IO_L21P_5	AJ12	I/O
5	IO_L22N_5	IO_L22N_5	AA13	I/O
5	IO_L22P_5	IO_L22P_5	AA12	I/O
5	IO_L23N_5	IO_L23N_5	AC13	I/O
5	IO_L23P_5	IO_L23P_5	AB13	I/O
5	IO_L24N_5	IO_L24N_5	AG13	I/O
5	IO_L24P_5	IO_L24P_5	AF13	I/O
5	IO_L25N_5	IO_L25N_5	AK13	I/O
5	IO_L25P_5	IO_L25P_5	AJ13	I/O
5	IO_L26N_5	IO_L26N_5	AB14	I/O
5	IO_L26P_5	IO_L26P_5	AA14	I/O

Table 110: FG1156 Package Pinout (Cont'd)

Bank	XC3S4000 Pin Name	XC3S5000 Pin Name	FG1156 Pin Number	Type
1	IO_L07N_1	IO_L07N_1	D27	I/O
1	IO_L07P_1	IO_L07P_1	E27	I/O
1	IO_L08N_1	IO_L08N_1	A27	I/O
1	IO_L08P_1	IO_L08P_1	B27	I/O
1	IO_L09N_1	IO_L09N_1	F26	I/O
1	IO_L09P_1	IO_L09P_1	G26	I/O
1	IO_L10N_1/VREF_1	IO_L10N_1/VREF_1	C26	VREF
1	IO_L10P_1	IO_L10P_1	D26	I/O
1	IO_L11N_1	IO_L11N_1	H25	I/O
1	IO_L11P_1	IO_L11P_1	J25	I/O
1	IO_L12N_1	IO_L12N_1	F25	I/O
1	IO_L12P_1	IO_L12P_1	G25	I/O
1	IO_L13N_1	IO_L13N_1	C25	I/O
1	IO_L13P_1	IO_L13P_1	D25	I/O
1	IO_L14N_1	IO_L14N_1	A25	I/O
1	IO_L14P_1	IO_L14P_1	B25	I/O
1	IO_L15N_1	IO_L15N_1	A24	I/O
1	IO_L15P_1	IO_L15P_1	B24	I/O
1	IO_L16N_1	IO_L16N_1	J23	I/O
1	IO_L16P_1	IO_L16P_1	K23	I/O
1	IO_L17N_1/VREF_1	IO_L17N_1/VREF_1	F23	VREF
1	IO_L17P_1	IO_L17P_1	G23	I/O
1	IO_L18N_1	IO_L18N_1	D23	I/O
1	IO_L18P_1	IO_L18P_1	E23	I/O
1	IO_L19N_1	IO_L19N_1	A23	I/O
1	IO_L19P_1	IO_L19P_1	B23	I/O
1	IO_L20N_1	IO_L20N_1	K22	I/O
1	IO_L20P_1	IO_L20P_1	L22	I/O
1	IO_L21N_1	IO_L21N_1	G22	I/O
1	IO_L21P_1	IO_L21P_1	H22	I/O
1	IO_L22N_1	IO_L22N_1	C22	I/O
1	IO_L22P_1	IO_L22P_1	D22	I/O
1	IO_L23N_1	IO_L23N_1	H21	I/O
1	IO_L23P_1	IO_L23P_1	J21	I/O
1	IO_L24N_1	IO_L24N_1	F21	I/O
1	IO_L24P_1	IO_L24P_1	G21	I/O
1	IO_L25N_1	IO_L25N_1	C21	I/O
1	IO_L25P_1	IO_L25P_1	D21	I/O
1	IO_L26N_1	IO_L26N_1	A21	I/O
1	IO_L26P_1	IO_L26P_1	B21	I/O

Table 110: FG1156 Package Pinout (Cont'd)

Bank	XC3S4000 Pin Name	XC3S5000 Pin Name	FG1156 Pin Number	Type
3	IO_L48P_3	IO_L48P_3	AB24	I/O
3	N.C. (◆)	IO_L49N_3	AA26	I/O
3	N.C. (◆)	IO_L49P_3	AA25	I/O
3	IO_L50N_3	IO_L50N_3	Y25	I/O
3	IO_L50P_3	IO_L50P_3	Y24	I/O
3	N.C. (◆)	IO_L51N_3	V24	I/O
3	N.C. (◆)	IO_L51P_3	W24	I/O
3	VCCO_3	VCCO_3	AA23	VCCO
3	VCCO_3	VCCO_3	AB23	VCCO
3	VCCO_3	VCCO_3	AB29	VCCO
3	VCCO_3	VCCO_3	AB33	VCCO
3	VCCO_3	VCCO_3	AD27	VCCO
3	VCCO_3	VCCO_3	AD31	VCCO
3	VCCO_3	VCCO_3	AG28	VCCO
3	VCCO_3	VCCO_3	AG32	VCCO
3	VCCO_3	VCCO_3	AL32	VCCO
3	VCCO_3	VCCO_3	W23	VCCO
3	VCCO_3	VCCO_3	W31	VCCO
3	VCCO_3	VCCO_3	Y23	VCCO
3	VCCO_3	VCCO_3	Y27	VCCO
4	IO	IO	AD18	I/O
4	IO	IO	AD19	I/O
4	IO	IO	AD20	I/O
4	IO	IO	AD22	I/O
4	IO	IO	AE18	I/O
4	IO	IO	AE19	I/O
4	IO	IO	AE22	I/O
4	N.C. (◆)	IO	AE24	I/O
4	IO	IO	AF24	I/O
4	N.C. (◆)	IO	AF26	I/O
4	IO	IO	AG26	I/O
4	IO	IO	AG27	I/O
4	IO	IO	AJ27	I/O
4	IO	IO	AJ29	I/O
4	IO	IO	AK25	I/O
4	IO	IO	AN26	I/O
4	IO/VREF_4	IO/VREF_4	AF21	VREF
4	IO/VREF_4	IO/VREF_4	AH23	VREF
4	IO/VREF_4	IO/VREF_4	AK18	VREF
4	IO/VREF_4	IO/VREF_4	AL30	VREF